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(54) SILVER-PALLADIUM-PLATINUM COMPOSITE PULVERIZED POWDER AND ITS PRODUCTION

(57)Abstract:

PURPOSE: To improve conductive paste characteristics by uniformly dispersing palladium and platinum in a pulverized silver powder and also to provide a means of obtaining a composite pulverized powder where palladium and platinum are uniformly dispersed in a pulverized silver powder.

CONSTITUTION: The composite pulverized powder is characterized by being prepared by uniformly dispersing palladium and platinum in a pulverized silver powder and exerting heat treatment at 200-600°C, and further, the above means is characterized by using chemical reduction or hydrogen reduction reaction at the time of uniformly dispersing palladium or platinum in a pulverized silver powder.

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